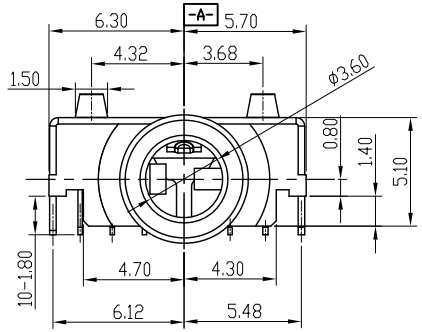
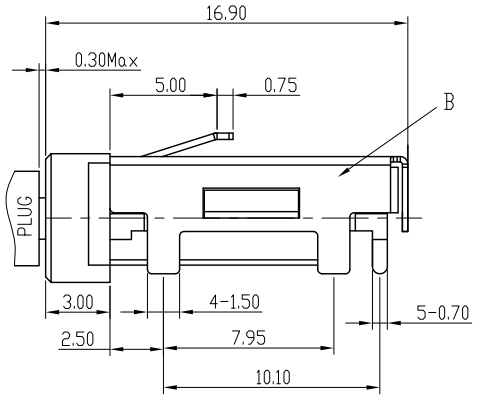
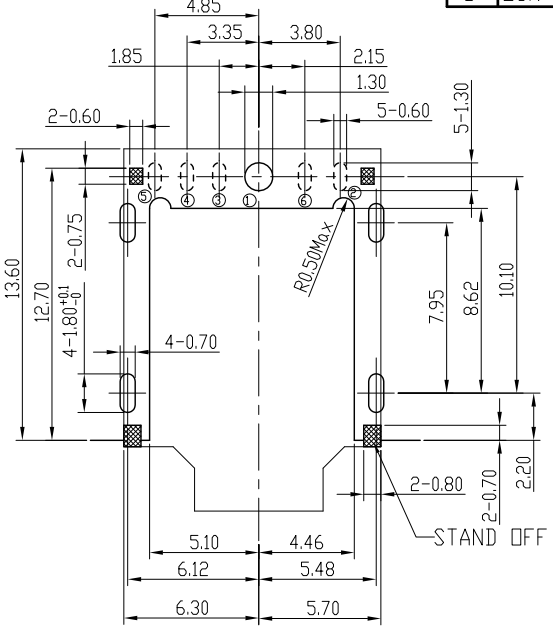
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR No.:T120522-14A	Mars	2012.05.31
B	ECN NO.S130136	Angus	2013.06.27

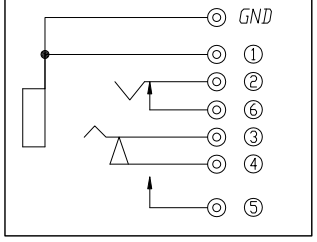


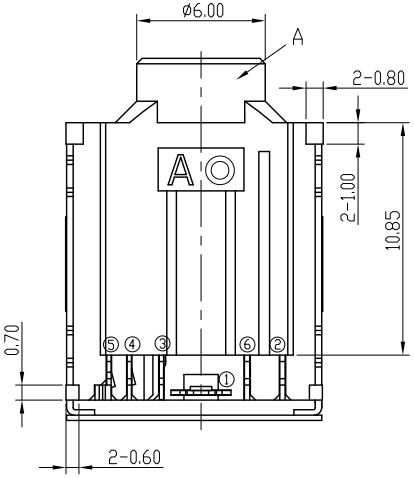


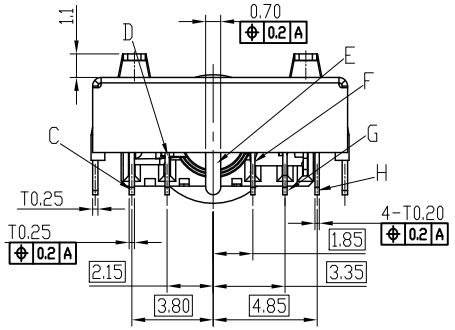


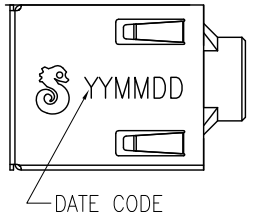
RECOMMENDED PCB LAYOUT
TOP VIEW ; TOL.±0.05
PCB THICKNESS: 1.2mm

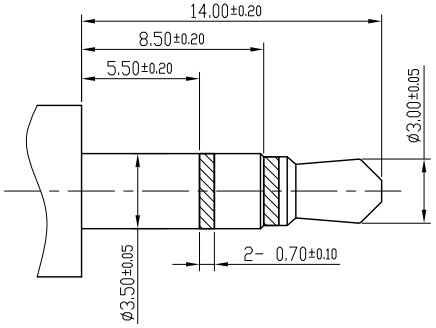
SCHEMATIC
② AND ⑥ NORMAL CLOSE
④ AND ⑤ NORMAL OPEN











SPECIFICATIONS :
1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
2. INSULATION VOLTAGE WITHSTAND : 500V AC FOR ONE MINUTE.
3. CONTACT RESISTANCE : 30mΩ MAX.
4. UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5~35°C IN TEMPERATURE AND 45~85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60~70% IN HUMIDITY.
5. LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
6. INSERTION FORCE :0.4 ~ 3Kgf.
7. WITHDRAWAL FORCE :0.3 ~ 2Kgf.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE :50MΩ MIN.
10. MARKING: MARK" " ON TOP OF CONNECTOR.
11. PACKAGING : TAPE & REEL.
12. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
13. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ◎
14. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON THE PACKAGING:
15. FOR LEAD-FREE PROCESS.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	MAKE TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD PLATD ALL OVER Ni 60u"Min.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD PLATD ALL OVER Ni 60u"Min.
F	RING SPRING	1	PHOSPHOR BRONZE 0.2t	GOLD PLATD ALL OVER Ni 60u"Min.
E	EARTH	1	PHOSPHOR BRONZE 0.2t	GOLD PLATD ALL OVER Ni 60u"Min.
D	SHUNT TERMINAL	1	ALLOY COPPER 0.2t	GOLD PLATD ALL OVER Ni 60u"Min.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	GOLD PLATD ALL OVER Ni 60u"Min.
B	SHELL	1	SPCC-SD 0.25t	Ni 60u"Min.
A	BODY	1	HIGH TEMP.THERMOPLASTIC	UL 94V-0 & BLACK

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: ANGLES:
X :±0.5 X :±2°
X.X :±0.3 X.X :±1°
X.XX :±0.2

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	ø3.5 SINKING TYPE AUDIO JACK			
DWN	Angus	PART NO. 2SJ1012-100111F		
CHKD	Cerry	SCALE:4:1	UNIT: mm	
APVD	Max	SIZE: A3	SHEET: 1OF1	REV: B

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